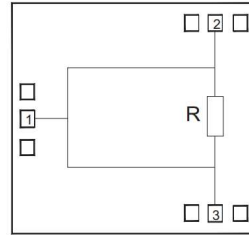


### Performance

- Frequency: 18~40GHz
- Insertion loss: 0.8dB
- Chip size: 1.67\*1.40\*0.1mm

### Function Diagram

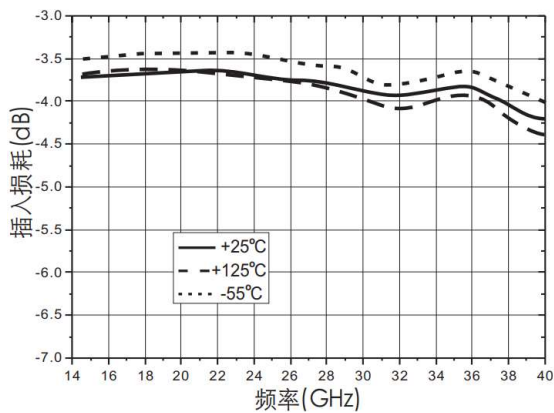


### Electrical Specifications (Ta=+25°C, 50Ω system)

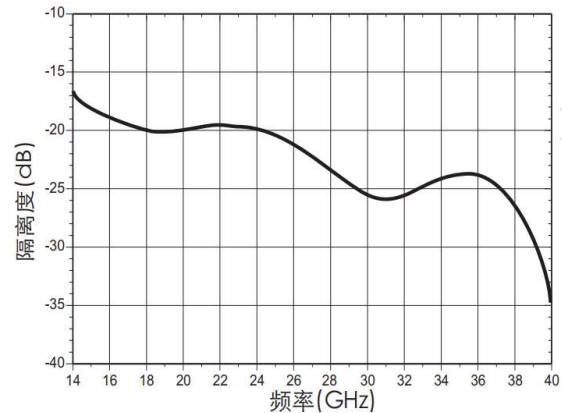
Parameter		Min	Typical	Max	Unit
Frequency Range		18~40			GHz
Insertion Loss	18~30GHz	-	0.8	1.2	dB
	30~40GHz	-	1.0	1.5	dB
Insertion Loss Ripple		-	±0.3	-	dB
Isolation		15	20	-	dB
Input Return Loss		15	18	-	dB
Output Return Loss		12	20	-	dB

### Test Curves

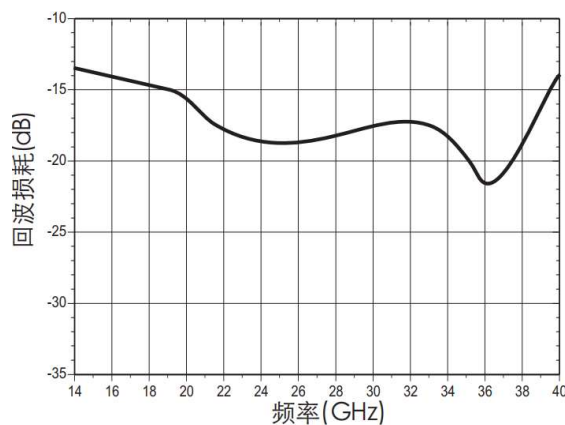
Insertion loss vs. Freq



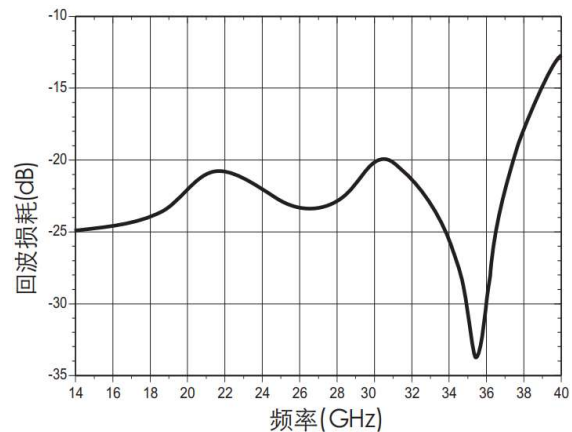
Isolation vs. Freq



Input Return Loss vs. Freq



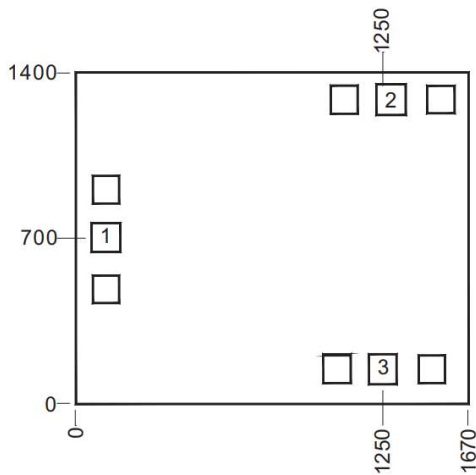
Output Return Loss vs. Freq



### Absolute Max Ratings

Parameter	Value
Input Signal Power	+37dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C
Static protection Grade (HBM)	Class 1A

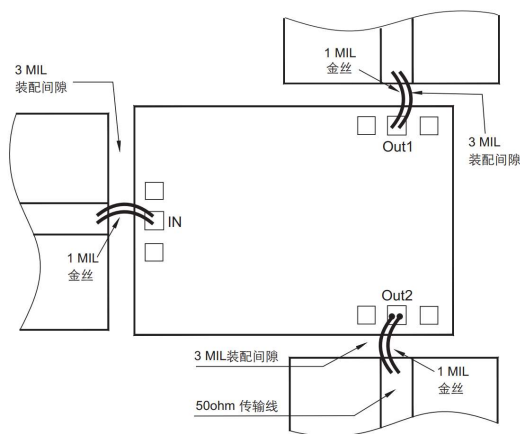
### Outline Size



### Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated  
Pads size: 120\*100 um
5. Don't bonding on thru holds
6. Tolerance: ±50um

### Assembly Diagram



### Bonding Definition

No.	Number	Description
1	IN	RF input, 50ohm
2,3	Out1,Out2	RF output, 50ohm
	GND	Bottom must be grounded